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Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation, and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!


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PACKAGE DIMENSIONS


NOTES:

1. Dimensions for all drawings are in inches (millimeters).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.

## FEATURES

- No contact switching
- 5.0 mm wide slot
- 0.5 mm aperture width
- Opaque black plastic housing
- Output configuration: Buffer open-collector
- TTL/CMOS compatible output
- Locating knobs on housing base for accurate mounting

NOTES (Applies to Max Ratings and Characteristics Tables.)

1. Derate power dissipation linearly $1.67 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $25^{\circ} \mathrm{C}$.
2. Derate power dissipation linearly $2.50 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $25^{\circ} \mathrm{C}$.
3. RMA flux is recommended.
4. Methanol or isopropyl alcohols are recommended as cleaning agents.
5. Soldering iron $1 / 16^{\prime \prime}(1.6 \mathrm{~mm})$ from housing.
6. As long as leads are not under any stress or spring tension.

ABSOLUTE MAXIMUM RATINGS $\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}\right.$ unless otherwise specified)

| Parameter | Symbol | Rating | Units |
| :--- | :---: | :---: | :---: |
| Operating Temperature | $\mathrm{T}_{\mathrm{OPR}}$ | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature | $\mathrm{T}_{\text {STG }}$ | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| Lead Temperature (Solder Iron) $)^{(3,4,5,6)}$ | $\mathrm{T}_{\text {SOL-I }}$ | 240 for 5 sec | ${ }^{\circ} \mathrm{C}$ |
| Lead Temperature (Solder Flow) $(3,4,5,6)$ | 260 for 10 sec | ${ }^{\circ} \mathrm{C}$ |  |
| EMITTER | $\mathrm{T}_{\text {SOL-F }}$ |  |  |
| Continuous Forward Current | $\mathrm{I}_{\mathrm{F}}$ | 50 | mA |
| Reverse Voltage | $\mathrm{V}_{\mathrm{R}}$ | 5 | V |
| Power Dissipation ${ }^{(1)}$ | $\mathrm{P}_{\mathrm{D}}$ | 100 | mW |
| SENSOR | $\mathrm{I}_{\mathrm{O}}$ | 50 | mA |
| Output Current | $\mathrm{V}_{\mathrm{CC}}$ | 16 | V |
| Supply Voltage | $\mathrm{V}_{\mathrm{O}}$ | 30 | V |
| Output Voltage | $\mathrm{P}_{\mathrm{D}}$ | 150 | mW |
| Power Dissipation ${ }^{(2)}$ |  |  |  |

## ELECTRICAL / OPTICAL CHARACTERISTICS ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ )

| PARAMETER <br> Operating Supply Voltage | TEST CONDITIONS | SYMBOL $\mathrm{V}_{\mathrm{CC}}$ | MIN. $4.5$ | TYP. | $\begin{gathered} \text { MAX. } \\ 16 \end{gathered}$ | UNITS <br> V |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| INPUT DIODE |  |  |  |  |  |  |
| Forward Voltage | $\mathrm{I}_{\mathrm{F}}=20 \mathrm{~mA}$ | $V_{F}$ | - |  | 1.7 | V |
| Reverse Leakage Current | $\mathrm{V}_{\mathrm{R}}=5 \mathrm{~V}$ | $\mathrm{I}_{\mathrm{R}}$ | - |  | 10 | $\mu \mathrm{A}$ |
| COUPLED |  |  |  |  |  |  |
| Operating Supply Current | $\mathrm{I}_{\mathrm{F}}=15 \mathrm{~mA}$ or $0 \mathrm{~mA}, \mathrm{~V}_{\mathrm{CC}}=16 \mathrm{~V}$ | $\mathrm{I}_{\mathrm{cc}}$ | - |  | 5 | mA |
| Low Level Output Voltage | $\mathrm{I}_{\mathrm{F}}=15 \mathrm{~mA}, \mathrm{~V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=360 \Omega$ | $\mathrm{V}_{\mathrm{OL}}$ | - |  | 0.4 | V |
| High Level Output Current | $\mathrm{I}_{\mathrm{F}}=0 \mathrm{~mA}, \mathrm{~V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{OH}}=30 \mathrm{~V}$ | $\mathrm{I}_{\mathrm{OH}}$ | - |  | 100 | $\mu \mathrm{A}$ |
| Turn on Threshold Current | $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=360 \Omega$ | $\mathrm{I}_{\mathrm{F}}(+)$ | - |  | 15 | mA |
| Turn off Threshold Current | $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=360 \Omega$ | $\mathrm{I}_{\mathrm{F}}(-)$ | 0.50 |  | - | mA |
| Hysteresis Ratio |  | $\mathrm{I}_{\mathrm{F}}(+) / \mathrm{I}_{\mathrm{F}}(-)$ |  | 1.2 |  |  |
| Propagation Delay | $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=360 \Omega$ | $\mathrm{t}_{\text {PLH, }} \mathrm{t}_{\text {PHL }}$ |  | 5 |  | $\mu \mathrm{s}$ |
| Output Rise and Fall Time | $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=360 \Omega$ | $\mathrm{t}_{\mathrm{r},} \mathrm{t}_{\mathrm{f}}$ |  | 70 |  | ns |

## TYPICAL PERFORMANCE CURVES

Fig. 1 Output Voltage vs. Input Current


Fig. 2 Normalized Threshold Current vs. Shield Distance


Fig. 3 Normalized Threshold Current vs. Supply Voltage


Fig. 5 Forward Current vs. Forward Voltage


Fig. 4 Normalized Threshold Current vs. Ambient Temperature


Fig. 6 Low Output Voltage vs. Output Current


Io - Output Current (mA)

Fig. 7 Response Time vs. Forward Current


Fig． 8 Switching Speed Test Circuit


Fig． 9 Typical Operating Circuit


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\begin{array}{llll}
\mathbf{R}_{1}=270 & \Omega & \mathrm{C}_{1}=15 \mathrm{pf} & \mathrm{C}_{1} \text { and } \mathrm{C}_{2} \text { include probe and } \\
\mathbf{R}_{2}=360 & \Omega & \mathrm{C}_{2}=20 \mathrm{pf} & \text { stray wire capacitance }
\end{array}
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Fig． 10 Switching Test Curve for Buffers


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